

LOC

EAST - [capacitor to via.wsp:1]											
File View Edit Tools Window Help											
<div> <div> <div>Pending</div> <div>Active</div> </div> <div> <div>1.1: (241) "tape carrier package" and "tape automated bonding"</div> </div> </div> <div> <div>Search</div> <div>View</div> <div>Browse</div> <div>Queue</div> <div>Clear</div> </div> <div> <div>BRS form</div> <div>IS&R form</div> <div>Image</div> <div>Text</div> </div>											
	U	I	Document ID	Iss	Page	Title	C rrent OR	Current XRef	Retrieval Classif	In	
1	<input type="checkbox"/>	<input type="checkbox"/>	US 20010026010 A1		52	Semiconductor device and process of production of same					Horiuchi, Michi Kurihara, Tak et al.
2	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20010026009 A1		45	Semiconductor device, a semiconductor module loaded with said					Tsuneda, Kens Sugano, Tosh et al.
3	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20010026008 A1		45	Semiconductor device, a semiconductor module loaded with said					Tsuneda, Kens Sugano, Tosh et al.
4	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 20010012643 A1		28	Package having very thin semiconductor chip, multichip module assembled by					Asada, Junichi
5	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6239496 B1	200 105 29	27	Package having very thin semiconductor chip, multichip module assembled by	257/777	257/685 : 257/686 : 257/698			Asada, Junichi
6	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6125042 A	200 009 26	10	Ball grid array semiconductor package having improved EMI characteristics	361/760	257/737 : 257/738 : 257/779			Verdi, Fred W. et al.
7	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6114754 A	200 009 05	19	Tape automated bonding film	257/668	257/673 : 257/778			Kata, Keiichiro
8	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5895969 A	199 904 20	16	Thin type semiconductor device, module structure using the device and	257/696	257/676			Masuda, Masa et al.
9	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5894107 A	199 904 13	11	Chip-size package (CSP) using a multi-layer laminated lead frame	174/52.2	174/52.4 : 257/676 : 257/693			Lee, Kyu Jin et al.
10	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5821614 A	199 810 13	30	Card type semiconductor device	257/679	235/492 : 257/712 : 257/713			Hashimoto, No et al.
11	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5818105 A	199 810 06	16	Semiconductor device with plastic material covering a semiconductor chip	257/696	257/695 : 257/701 : 257/703			Kouda, Tsunen
12	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5723903 A	199 14	14	Thin type semiconductor device, module	257/696	257/676			Masuda, Masa

EAST [capacitor to via.wsp:1]

File View Edit Tools Window Help

Pending
Active

1.1: (241) "tape carrier package" and "tape automated bonding"

Search LV Browse Queue Clear

BRS form ISIR form Image Text

	U	I	Document ID	Iss	Page	Title	Current OF	Current XRef	Retrieval Classif	In
6	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6125042 A	200	10	Ball grid array semiconductor package having improved EMI characteristics	361/760	257/737 : 257/738 : 257/779		Verdi, Fred W. , et al.
7	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 6114754 A	200	19	Tape-automated bonding film	257/668	257/673 : 257/778		Kata, Keiichiro
8	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5895969 A	199	16	Thin type semiconductor device, module structure using the device and	257/696	257/676		Masuda, Masa , et al.
9	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5894107 A	199	11	Chip-size package (CSP) using a multi-layer laminated lead frame	174/52.2	174/52.4 : 257/676 : 257/693		Lee, Kyu Jin , et al.
10	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5821614 A	199	30	Card type semiconductor device	257/679	235/492 : 257/712 : 257/713		Hashimoto, No , et al.
11	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5818105 A	199	16	Semiconductor device with plastic material covering a semiconductor chip	257/696	257/695 : 257/701 : 257/703		Kouda, Tsunen
12	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5723903 A	199	14	Thin type semiconductor device, module structure using the device and	257/696	257/676 : 257/686 : 257/787		Masuda, Masa , et al.
13	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5586270 A	199	21	Method and apparatus for upgrading a central processing unit and	710/301	710/13 : 711/130		Rotier, Michael , et al.
14	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5446313 A	199	13	Thin type semiconductor device and module structure using the device	257/666	257/686 : 257/702 : 257/787		Masuda, Masa , et al.
15	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5410182 A	199	9	High density semiconductor device having inclined chip mounting	257/692	257/775 : 257/776		Kurafuchi, Kazi , et al.
16	<input checked="" type="checkbox"/>	<input type="checkbox"/>	US 5349236 A	199	17	Reusable fixture for carrier tape	257/701	206/713 : 257/668 : 257/727		Oshino, Fumio , et al.

Start

4:55 PM

L Number	Hits	Search Text	DB	Time stamp
-	241	"tape carrier package" and "tape automated bonding"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 16:45
-	184	("tape carrier package" and "tape automated bonding") and semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 16:46
-	16	((("tape carrier package" and "tape automated bonding") and semiconductor) and (thin near3 package)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 16:55
-	6786	("257/684,690,707,737,778,668,666").CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 16:56
-	0	("4 and "tape carrier package").PN.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 16:57
-	95	((("257/684,690,707,737,778,668,666").CCLS.) and "tape carrier package"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 16:57
-	0	((("257/684,690,707,737,778,668,666").CCLS.) and "tape carrier package") and "Tape automated bonding") and leadframe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 16:58
-	408	((("257/684,690,707,737,778,668,666").CCLS.) and leadframe	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 16:58
-	0	((("257/684,690,707,737,778,668,666").CCLS.) and leadframe) and "tape carrier package"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 16:58
-	34	((("257/684,690,707,737,778,668,666").CCLS.) and "tape carrier package") and "Tape automated bonding"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 17:08
-	308	((("257/684,690,707,737,778,668,666").CCLS.) and (col or loc)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 17:09
-	2	((("257/684,690,707,737,778,668,666").CCLS.) and (col or loc)) and "tape carrier package"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 17:11

-	33	((("257/684,690,707,737,778,668,666").CCLS.) and ("chip\$on\$lead" or chip-on-lead))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 17:12
-	0	((("257/684,690,707,737,778,668,666").CCLS.) and ("chip\$on\$lead" or chip-on-lead)) and "tape carrier package"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 17:13
-	17	((("257/684,690,707,737,778,668,666").CCLS.) and ("chip\$on\$lead" or chip-on-lead)) and "thin package"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/01/25 17:13